

REMARKS

This is intended as a full and complete response to the Office Action dated November 21, 2003, having a shortened statutory period for response extended one-month to expire on March 23, 2004. Claims 1-20 remain pending in the application and are shown above. Claims 1-20 are rejected by the Examiner. Reconsideration of the rejected claims is requested for reasons presented below.

Claims 1-20 stand rejected under 35 USC § 103(a) as being unpatentable over Applicant's Admitted Prior Art (AAPA) in view of *Kaufman '293 et al.* The Examiner asserts that it would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified the method and composition of the Applicants Admitted Prior Art by adding a complexing agent to the solution as taught by *Kaufman '293 et al.* Applicants respectfully respond to this rejection.

Applicants Admitted Prior Art (AAPA) discloses an explanation of pressure sensitive slurries in the background of the specification and a list of commercial compositions that are believed to be pressure sensitive slurries. Applicants Admitted Prior Art does not disclose the components of a pressure sensitive slurry.

Kaufman '293 et al. discloses a chemical mechanical polishing slurry for polishing copper alloy, titanium, titanium nitride, tantalum, tantalum nitride, comprising an oxidizing agent, a complexing agent, an abrasive, and an optional surfactant, and the slurry does not contain a separate film-forming agent. *Kaufman '293 et al.* does not suggest or motivate that the slurries of *Kaufman '293 et al.* are pressure sensitive solutions.

Unlike U.S. Patent Serial No. 6,447, 371 (*Kaufman et al.*), *Kaufman '293 et al.* teaches a composition free of a separate film-forming agent, such as BTA, a passivating agent, and, thus, teaches away from the present invention of a composition having a corrosion inhibitor as recited in claims 1, 9, and 19, and claims dependent thereon.

Therefore, the combination of AAPA and *Kaufman, et al.* does not teach, show, or suggest a composition for planarizing a substrate comprising a pressure sensitive solution, one or more chemical agents comprising a complexing agent for complexing with a metal or oxidized metal, wherein the complexing agent is selected from the group


of ammonium salts of organic acids, amines, amine derivatives, compounds with one or more peroxy acid groups, ions of at least one transition metal, and combinations thereof, and a corrosion inhibitor, as recited in claim 1, and claims dependent thereon. Withdrawal of the rejection is respectfully requested.

Further, the combination of AAPA and *Kaufman, et al.* does not teach, show, or suggest a method for planarizing a substrate surface, comprising applying a composition to polishing media, the composition comprising a pressure sensitive solution, one or more chemical agents comprising a complexing agent for complexing with a metal or oxidized metal, wherein the complexing agent is selected from the group of ammonium salts of organic acids, amines, amine derivatives, compounds with one or more peroxy acid groups, ions of at least one transition metal, and combinations thereof, and a corrosion inhibitor, and polishing the substrate surface, as recited in claim 9, and claims dependent thereon. Withdrawal of the rejection is respectfully requested.

Additionally, the combination of AAPA and *Kaufman, et al.* does not teach, show, or suggest a method for removal of a copper containing layer from a substrate surface, comprising applying a composition to a polishing media, the composition comprising a pressure sensitive solution, about 1 wt.% or less of a solution containing ammonium salts of organic acids, about 10 wt.% or less abrasive particles, and a corrosion inhibitor, and polishing the substrate surface with the polishing media, as recited in claim 19, and claims dependent thereon. Withdrawal of the rejection is respectfully requested

In conclusion, the references cited by the Examiner, alone or in combination, do not teach, show, or suggest the invention as claimed. Having addressed all issues set out in the office action, Applicant respectfully submits that the claims are in condition for allowance and respectfully request that the claims be allowed.

Respectfully submitted,



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